

Section

HV Multifunction

Application

Field
Laboratory
Production



PRODUCT BENEFITS

No silicone
Ball bearings for an easier rotation of the tool
Low roughness over insulation

TOOL CAPACITY

Diameter	40 - 90 mm 1,575 - 3,543 inch
Bonded semicon thickness capacity	2,5 mm / 0,098 in
Remaining length of the semicon	55 mm / 2,165 in
Insulation thickness capacity	35 mm / 1,378 in
Guiding	By ball bearings

TOOL DIMENSIONS

Length	460 mm
Width	155 mm
Height	150 mm
Weight without box	3,9 Kg
Packaging	Case

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Multifunction tool for bonded semiconductor and insulation

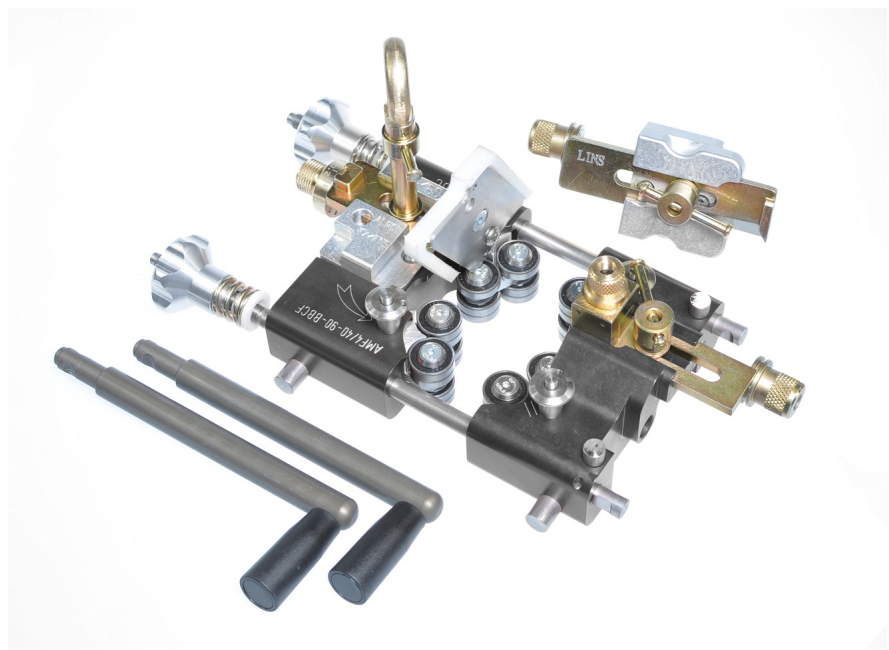
TO DO WHAT

The CAMF4/40-90-BBCF enables the user :
-To remove the bonded semiconductor
-To remove the insulation

The ball bearings in contact with the cable enable an easy rotation of the tool

Bonded semiconductor removal : Very steady (16 ball bearings rolling around the cable), shaping the cable round over the insulation , constant diameter over the insulation, prevent the blade from digging into the insulation, perform a chamfer on transition between the insulation and the semiconductor

Insulation removal : Back-iron that enables the user to tune the pitch of the tool thus making the rotation of the tool easy when removing the insulation



Options

- BMF/40-90 - Thrust to stop the tool
- K7/GNS - Blade support to remove outer sheath semiconductor layer
- K7/PNS4 - Blade support to lengthen chamfered transition and make groove/slot
- K7/SNS4 - To remove semiconductor with straight transition between insulation and semi

Spare part

- LFNS - Spare blade for bonded semiconductor
- LINS - Spare blade for insulation

Associated tool

- DMSR/40-90 - Reinforced stripping tool for hard outer sheath (PE, PEHD, Lead)
- CHN4/50-110 NS - Tool to taper XLPE insulation
- GRI - Scraper for residues of bonded semiconductor

HV cables Tools

CAMF4/40-90-BBCF



Part Number	Diameter	Tool capacity				Dimensions			Packaging
		Bonded semicon thickness capacity	Remaining length of the semicon	Insulation thickness capacity	Guiding	Length	Width	Height	
CAMF4/40-90-BBCF	40 - 90 mm 1,575 - 3,543 in	2,5 mm / 0,098 in	55 mm / 2,165 in	35 mm / 1,378 in	By ball bearings	460 mm 18,110 in	155 mm 6,102 in	150 mm 5,906 in	case
CAMF5/55-160-BBCF	55 - 160 mm 2,165 - 6,299 in	3 mm / 0,118 in	80 mm / 3,150 in	35 mm / 1,378 in	By ball bearings	700 mm 27,559 in	255 mm 10,039 in	180 mm 7,087 in	case
CAMF5/55-160-NSCF	55 - 160 mm 2,165 - 6,299 in	3 mm / 0,118 in	80 mm / 3,150 in	35 mm / 1,378 in	By wheels rolling	700 mm 27,559 in	255 mm 10,039 in	180 mm 7,087 in	case